



Material Content Data Sheet



Sales Product Name		TLE7241E		Issued		2. August 2018		
MA#		MA001110592						
Package		PG-DSO-20-67		Weight*		587.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.861	1.85	1.85	18489	18489
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		80	
	non noble metal	zinc	7440-66-6	0.187	0.03		319	
	non noble metal	iron	7439-89-6	3.750	0.64		6383	
wire	non noble metal	copper	7440-50-8	152.251	25.92	26.60	259180	265962
	non noble metal	copper	7440-50-8	0.529	0.09	0.09	900	900
	encapsulation	organic material	carbon black	1333-86-4	0.823	0.14		1401
encapsulation	plastics	epoxy resin	-	37.847	6.44		64428	
	inorganic material	silicondioxide	60676-86-0	372.714	63.45	70.03	634476	700305
leadfinish	non noble metal	tin	7440-31-5	4.487	0.76	0.76	7638	7638
plating	noble metal	silver	7440-22-4	0.706	0.12	0.12	1202	1202
glue	plastics	epoxy resin	-	0.808	0.14		1376	
	noble metal	silver	7440-22-4	2.425	0.41	0.55	4128	5504
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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